

# LNJ026X8ARA1

## High Bright Surface Mounting Chip LED

UTSS Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	10	mA
Pulse forward current *	$I_{FP}$	40	mA
Reverse voltage	$V_R$	5	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

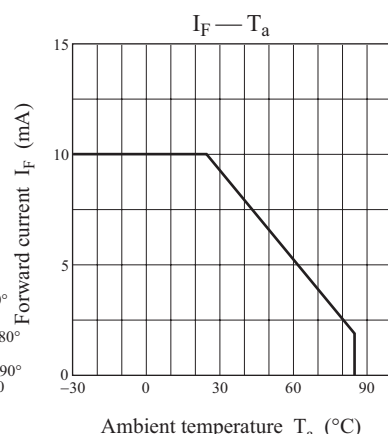
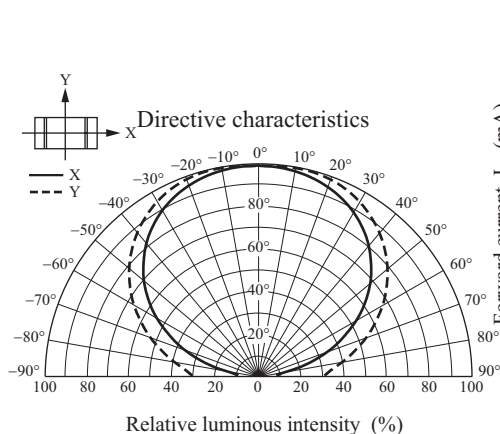
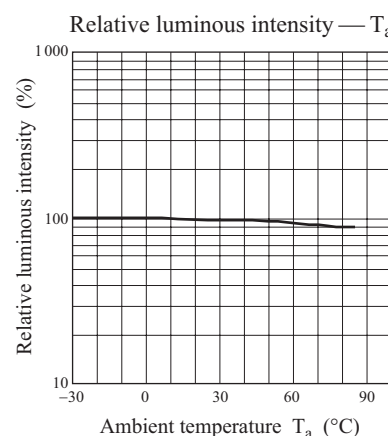
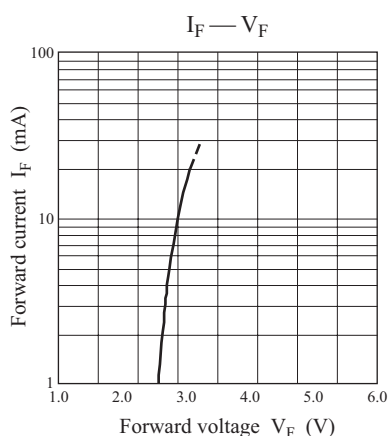
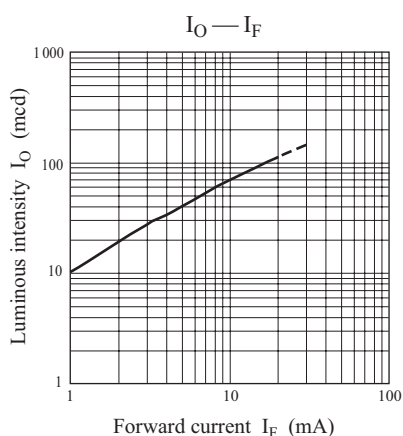
■ Lighting Color

- White

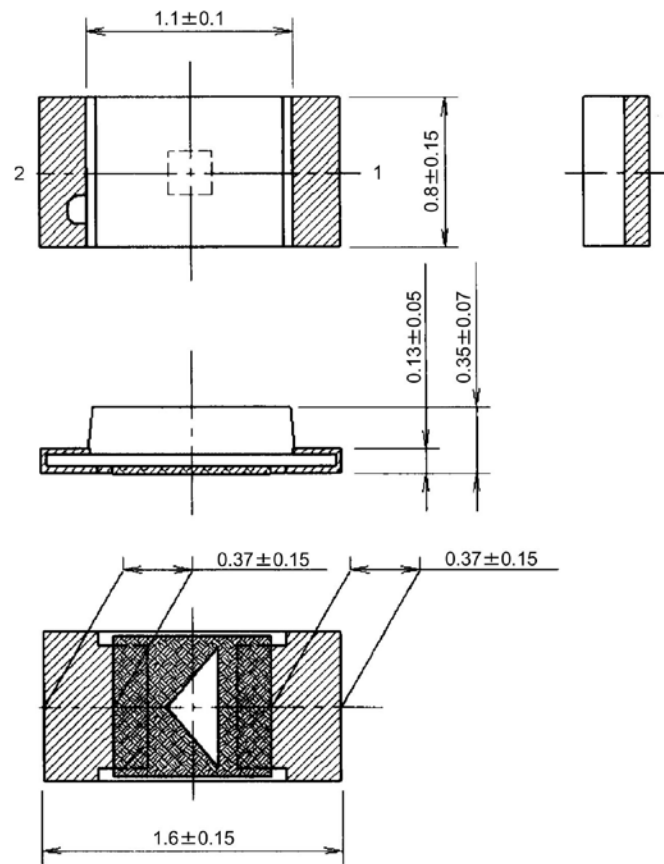
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$	$I_F = 5 \text{ mA}$	24	40	81	mcd
Reverse current	$I_R$	$V_R = 5 \text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 5 \text{ mA}$		2.9	3.2	V
Chromaticity coordinates	x	$I_F = 5 \text{ mA}$	0.229		0.302	—
	y	$I_F = 5 \text{ mA}$	0.215		0.311	—



## ■ Package (Unit: mm)



- Pin name
- 1: Anode
- 2: Cathode

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